

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	194	laser with defect with (within inside below) with (semiconductor silicon nonmetal\$5 wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 10:55
L4	96	laser with defect near3 (within inside below) with (semiconductor silicon nonmetal\$5 wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 10:58
L5	5	4 same (cut\$4 cleav\$4 separat\$4 dic\$4) with (wafer semiconductor silicon nonmetal\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 11:10
L6	149	laser and defect and (within inside below) and (semiconductor silicon nonmetal\$5 wafer)	JPO	OR	ON	2007/02/22 11:07
L7	10	6 and (cut\$4 cleav\$4 separat\$4 dic\$4) with (wafer semiconductor silicon nonmetal\$5)	JPO	OR	ON	2007/02/22 11:00
L8	132	6 not inspect\$4	JPO	OR	ON	2007/02/22 11:07
L9	66	laser and defect with (within inside below) and (semiconductor silicon nonmetal\$5 wafer)	JPO	OR	ON	2007/02/22 11:09
L10	59	9 not inspect\$4	JPO	OR	ON	2007/02/22 11:07
L11	1522	laser with (within inside below) with (semiconductor silicon nonmetal\$5 wafer)	JPO	OR	ON	2007/02/22 11:17
L12	148	11 and (cut\$4 cleav\$4 separat\$4 dic\$4) with (wafer semiconductor silicon nonmetal\$5)	JPO	OR	ON	2007/02/22 11:17
L13	75	12 not semiconductor adj laser	JPO	OR	ON	2007/02/22 11:17
L14	74	13 not inspect\$4	JPO	OR	ON	2007/02/22 11:17
L15	56	laser with (form\$3 creat\$4 manufactur\$4) with (within inside below) with (semiconductor silicon nonmetal\$5 wafer) and (cut\$4 cleav\$4 separat\$4 dic\$4) with (semiconductor silicon nonmetal\$5 wafer) not (semiconductor near laser) not inspect\$4	JPO	OR	ON	2007/02/22 11:21

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L16	559	laser with (form\$3 creat\$4 manufactur\$4) with (within inside below) with (semiconductor silicon nonmetal\$5 wafer) and (cut\$4 cleav\$4 separat\$4 dic\$4) with (semiconductor silicon nonmetal\$5 wafer) not (semiconductor near laser) not inspect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 11:22
L17	31	laser with (form\$3 creat\$4 manufactur\$4) with ((within inside below) near3 (defect focus\$4 crack\$4)) with (semiconductor silicon nonmetal\$5 wafer) and (cut\$4 cleav\$4 separat\$4 dic\$4) with (semiconductor silicon nonmetal\$5 wafer) not (semiconductor near laser) not inspect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 11:28
L18	3	"2002105388"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 11:27
L19	0	("2006/0021978").URPN.	USPAT	OR	ON	2007/02/22 11:27
L20	3	laser with scrib\$4 with ((under within inside below) near3 surface) with (silicon wafer semiconductor nonmetal\$4) and (focus\$4 with ((under within inside below) near3 surface))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 11:44
L21	13	(laser with scrib\$4 with (silicon wafer semiconductor nonmetal\$4)) and (focus\$4 with ((under within inside below) near3 surface)) not 20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:26
L22	1	("6864457").PN.	USPAT; USOCR	OR	OFF	2007/02/22 12:07
L23	3	(laser with scrib\$4 with (silicon wafer semiconductor nonmetal\$4)) and (focus\$4 with ((under within inside below) near3 surface)) and polariz\$9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:10
L24	49	(laser with scrib\$4 with (silicon wafer semiconductor nonmetal\$4)) and (laser beam) with polariz\$9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:11

## EAST Search History

L25	12	(laser with scrib\$4 with (silicon wafer semiconductor nonmetal\$4)) and (laser beam) with polariz\$9 with (form\$3 formation defect point)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:11
L26	8	21 and (nd yag ndyag "nd:yag")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:27
L27	4	21 and (nd yag ndyag "nd:yag") and (ps pico picosecond "pico second")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:34
L28	32	scrib\$3 same laser same (nd yag ndyag "nd:yag") same (ps pico picosecond "pico second")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:30
L30	27	28 and scrib\$3 with (semiconductor wafer silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:31
L31	1589	(nd yag ndyag "nd:yag") same (ps pico picosecond "pico second") with ("10" "100")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:31
L32	0	30 and 31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:36
L33	1	24 and 31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:36
L34	6	16 and 31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:36
L35	3	31 and (laser with (silicon wafer) with cut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 12:38

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L36	89	31 and (laser with (silicon wafer)) not 35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:01
L37	40	(laser with (silicon wafer)) and (collimating with optic) and (dichroic with (rotary rotat\$4) with mirror) and (focus\$3 near3 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:02
L38	0	(laser with (silicon wafer) with (cut\$4 separat\$4 scrib\$4 dice dicing)) and (collimating with optic) and (dichroic with (rotary rotat\$4) with mirror) and (focus\$3 near3 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:03
L39	40	((silicon wafer) with (cut\$4 separat\$4 scrib\$4 dice dicing)) and (collimating with optic) and (dichroic with (rotary rotat\$4) with mirror) and (focus\$3 near3 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:05
L40	40	((silicon wafer) near5 (cut\$4 separat\$4 scrib\$4 dice dicing)) and (collimating with optic) and (dichroic with (rotary rotat\$4) with mirror) and (focus\$3 near3 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:05
L41	2	(laser near5 (cut\$4 separat\$4 scrib\$4 dice dicing)) and (collimating with optic) and (dichroic with (rotary rotat\$4) with mirror) and (focus\$3 near3 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:06
L42	7	(laser near5 (cut\$4 separat\$4 scrib\$4 dice dicing)) and (collimat\$3 with optic) and (dichroic with (rotary rotat\$4) with mirror) and (focus\$3 near3 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:08
L43	0	((scrib\$4 dice dicing) with (wafer silicon)) and (collimat\$3 with optic) and (dichroic with (rotary rotat\$4) with mirror) and (focus\$3 near3 lens)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:21
L47	1	("3626141").PN.	USPAT; USOCR	OR	OFF	2007/02/22 13:22
L48	1	47 and (nd yag)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:24

## EAST Search History

L49	1	47 and (nd yag) and (focus\$4 with spot with below with surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:24
L50	17	laser with (scrib\$4 dice dicing) and (nd yag ndyag "nd:yag") same (ps pico picosecond "pico second") with ("10" "100")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/22 13:32